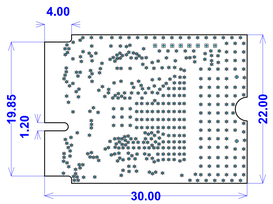
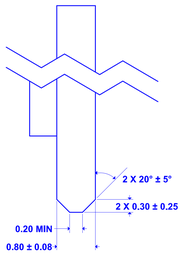
REV	ECO	Comments	Date
1		Initial Release	12-05-2023

Symbol	Hit Count	Finished Hole Size	Plated	Drill Layer Pair	Hole Type
○	2	0.900mm (35.43mil)	PTH	Top Layer - Bottom Layer	Round
□	8	0.711mm (28.00mil)	PTH	Top Layer - Bottom Layer	Round
✡	436	0.203mm (8.00mil)	PTH	Top Layer - Bottom Layer	Round
	446 Total				





NOTE: HARD GOLD ON FINGERS 30-50 MICRO INCHES OF GOLD OVER 150-200 MICRO INCHES OF NICKLE MINIMUM

THIS PCB TO BE MANUFACTURED TO MEET ALL ACCEPTANCE LEVELS OF A CLASS 2 PCB PER ANSI/IPC-A-600G.

MATERIAL: FR-4 or Equivalent

- [X] MULTILAYER [4] LAYERS [X] CONTROLLED IMPEDANCE
- Cu WEIGHT EXTERNAL LAYERS [1.4 mils] FINISHED
- Cu WEIGHT INTERNAL LAYERS [1.4 mils] FINISHED
- FINISHED OVERALL THICKNESS [0.8] mm ± [0.08mm]
- COPPER THIEVING ALLOWED [ ] YES [X] NO
- VIA TENTING ALLOWED [X] YES [ ] NO

FINISH:

- [ ] LEAD-FREE HOT AIR LEVELING
- [X] IMMERSION GOLD
- [ ] IMMERSION TIN
- [ ] SMOBC WITH SELECTIVE GOLD PLATING ON LANDS INDICATED. 1um GOLD OVER 5-10 um NICKEL

SOLDERMASK [DYNACHEM EPIC 200 LPI OR EQUIVALENT]

SOLDERMASK COLOR [GREEN HIGH GLOSS]

SILKSCREEN COLOR [WHITE]

DRILLING: [ ] Blind / Burried Vias

Via Layer Pairs [Top-Bottom]

ALL HOLES TO BE LOCATED BY THE COORDINATES FROM THE NC DRILL DATA PROVIDED.

USE ARTWORK SET NO. [04-11937-R1] PCB REV [1]

ALL UL LOGO, MANUFACTURER'S ID, AND DATE CODES SHOULD NOT BE PLACED ON MODULE CAN TRY PLACING LOGO'S ON PANEL

ANY ALTERNATIVES TO THE ABOVE SPECIFICATIONS MUST FIRST BE APPROVED.

LAYER STACK-UP

Layer Description	Thickness after Lamination (mils)	DIFF IMP (ohm) +/-10%	DIFF TRACE WIDTH/ SPACING	Reference layer
PRIMARY SIDE, SILK SCREEN				
PRIMARY SIDE, SOLDER MASK	0.4			
PRIMARY SIDE, LAYER1(TOP LAYER)	1.4	90	7 mils / 4 mils	L2
DIELECTRIC	8			
INNER PLANE LAYER, LAYER2(GND)	1.4			
DIELECTRIC	10			
INNER PLANE LAYER, LAYER3(PWR)	1.4			
DIELECTRIC	8			
SECONDARY SIDE, LAYER4(BOTTOM LAYER)	1.4	90	7 mils / 4 mils	L3
SECONDARY SIDE, SOLDER MASK	0.4			
SECONDARY SIDE, SILK SCREEN				

(0.8 +/-0.08mm)

MICROCHIP
Microchip Technology Inc.
2355 W. Chandler Blvd.
Chandler, AZ 85224

TITLE: WlxCS02 M.2 Wi-Fi Module

PART NUMBER: EV59Y78A

PCB Layout Contact: Balaji Narayana	GERBER FILE: Fab Drawing (Bottom,Top Layer)		
Project owner: Nick Cheng	BOARD NUMBER: 04-11937	DOCUMENT NUMBER: 04-11937_FAB-D	DATE: 1/17/2024
PCB FILE NAME: WlxCS02 M.2 Wi-Fi Module.PcbDoc	LAYER NAME: FAB (M4)	REV: 1	10mm / 400mil